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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. 09/148,723
Priority Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Priority Group Art Unit 3729
Priority Examiner A. Tugbang
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

INFORMATION DISCLOSURE STATEMENT

References - - See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a divisional application of co-pending Application Serial No. 09/148,723, filed September 3, 1998, upon which the above-identified application relies for a priority dated under 35 U.S.C. §120. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. §1.98(d) and MPEP §609(2). As a courtesy, Applicant submits copies of the cited article and foreign references for review.

Citation of these references is respectfully requested.

Respectfully submitted,

Date: Oct 6, 2001


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